



## Material Content Data Sheet



Sales Product Name	IPSA70R2K0P7S			Issued		7. January 2020		
MA#	MA005413686							
Package	PG-TO251-3-347			Weight*		300.75 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.740	0.25	0.25	2461	2461
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		146	
	non noble metal	iron	7439-89-6	0.146	0.05		487	
	non noble metal	copper	7440-50-8	146.214	48.61	48.67	486160	486793
wire	non noble metal	aluminium	7429-90-5	0.148	0.05	0.05	492	492
encapsulation	organic material	carbon black	1333-86-4	1.260	0.42		4190	
	plastics	epoxy resin	-	23.943	7.96		79610	
	inorganic material	silicondioxide	60676-86-0	100.812	33.52	41.90	335199	418999
leadfinish	non noble metal	tin	7440-31-5	3.774	1.25	1.25	12549	12549
solder	non noble metal	tin	7440-31-5	0.024	0.01		79	
	noble metal	silver	7440-22-4	0.030	0.01		99	
	non noble metal	lead	7439-92-1	1.134	0.38	0.40	3769	3947
heatspreader	inorganic material	phosphorus	7723-14-0	0.007	0.00		22	
	non noble metal	iron	7439-89-6	0.022	0.01		75	
	non noble metal	copper	7440-50-8	22.455	7.47	7.48	74662	74759
*deviation	< 10%	Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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